

LISTING OF CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A cooling device for an electronic equipment, comprising:

a first cooling panel ~~wherein~~ in which a first passage through which refrigerant circulates is directly formed;

a second cooling panel ~~wherein~~ in which a second passage through which said refrigerant circulates is directly formed, ~~said formed~~, said second cooling panel being disposed to oppose said first cooling panel; and

a circulation pump for circulating said refrigerant through said first passage and said second passage to thereby diffuse heat transferred to said first cooling panel and said second cooling panel, wherein:

said first cooling panel and said second cooling panel sandwich therebetween an electronic circuit substrate.

2. (Currently Amended) The cooling device for an electronic equipment according to claim 1, further comprising a coupling member bearing said first cooling panel and said second cooling panel for opening and closing with respect to each other, and said coupling ~~connecting~~ member has a flexibility.

3. (Currently Amended) The cooling device for an electronic equipment according to claim 1, wherein at least one of said first cooling panel and said second cooling panel includes a micro-channel structure within said first passage or said second passage, said micro-channel structure including a plurality of narrow passages having a width smaller than a width of said first passage or said second passage.
4. (Currently Amended) The cooling device for an electronic equipment according to claim ~~[[1]]~~ 3, wherein said at least one of said first cooling panel and said second cooling panel includes an area in which an air-cooled fin is formed on a surface thereof, said area being disposed downstream of said micro-channel structure.
5. (Currently Amended) The cooling device for an electronic equipment according to claim 4, wherein said first passage or said second passage in said area is wobbled.
6. (Previously Presented) The cooling device for an electronic equipment according to claim 4, wherein a cooling fan is disposed corresponding to said air-cooled fin.
7. (Previously Presented) The cooling device for an electronic equipment according to claim 1, wherein said circulation pump is fixed onto a surface of said second cooling panel.
8. (Previously Presented) The cooling device for an electronic equipment according to claim 1, wherein a reservoir communicated with said second passage is disposed on a surface of said second cooling panel.
9. (Previously Presented) The cooling device for an electronic equipment according to claim 1, wherein a reservoir communicated with said second passage is formed within said second cooling panel.

10. (Currently Amended) The cooling device for an electronic equipment according to claim 1, wherein at least one of said first cooling panel and said second cooling panel is formed by bonding together a top heat radiation panel and a bottom heat radiation panel, in at least one of which is formed a groove, both said top heat radiation panel and said bottom heat radiation panel being metallic.

11. (Previously Presented) The cooling device for an electronic equipment according to claim 1, wherein said first cooling panel has an area smaller than an area of said second cooling panel.

12. (Currently Amended) The cooling device for an electronic equipment according to claim 1, wherein said first passage has a width smaller than a width of said second passage.

13. (Previously Presented) The cooling device for an electronic equipment according to claim 1, wherein said first passage has a depth larger than a depth of said second passage.

14. (Previously Presented) An electronic equipment mounting thereon the cooling device for electronic equipment according to claim 1.

15. (New) The cooling device for an electronic equipment according to claim 10, wherein said at least one of said first cooling panel or said second cooling panel includes a strut between said top heat radiation panel and said bottom heat radiation panel.

16. (New) The cooling device for an electronic equipment according to claim 1, wherein a fan is attached to at least one of said first cooling panel or said second cooling panel.